## Harvatek Surface Mount CHIP LEDs Data Sheet T16P1IRP-20C-0006X2

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	***************************************			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 1/15

DISCLAIMER
LIFE SUPPORT POLICY
PRODUCT SPECIFICATIONS4
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION4
LABEL SPECIFICATIONS
ELECTRO-OPTICAL CHARACTERISTICS
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW SOLDERING
PRECAUTION FOR USE9
PACKAGING10
TAPE DIMENSION10REEL DIMENSION11PACKING11DRY PACK12BAKING12PRECAUTIONS12
HANDLING OF SILICONE RESIN LEDS13
REFLOW SOLDERING14
REWORKING
CAUTIONS OF PICK AND PLACE

7					
Official Product	HT Part No.T16P1IRP-20C-0006X2				
Tentative Product	******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 2/15	

### DISCLAIMER

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

## Life Support Policy

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 3/15

#### **Product Specifications**

Гур:850 nm @20mA/ T <sub>S</sub> = 25℃		
<b>20mA/ T</b> s= 25℃		
1.75-7.25 mW/sr		
<b>@20mA/ T₅= 25</b> ℃		
I.35-1.65 V		
@20mA/ T <sub>S</sub> = 25℃ ;Tolerance: <u>+</u> 0.1V		
< 100 μA		
@ V <sub>R</sub> = 5 V		
Clear	Silicon	
EIA 481-1A specs	Conductive black tape	
EIA 481-1A specs	Conductive black	
HT standard	Paper	
220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
HT standard	Paper	Non-specified
	.35-1.65 V 220mA/ $T_s$ = 25°C ;Tolerance: <u>+</u> 0.1V 100 $\mu$ A $V_R$ = 5 V Clear EIA 481-1A specs EIA 481-1A specs	$\begin{array}{c c} .35-1.65 \ V \\ \hline @ 20mA/ \ T_S = 25 \ \ \ \ C \ \ \ \ \ \ \ \ \ \ \ \ \ \ $

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv,  $\lambda_D$  and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note : This is shipped test conditions

%Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

#### ATTENTION: Electrostatic Discharge (ESD) protection



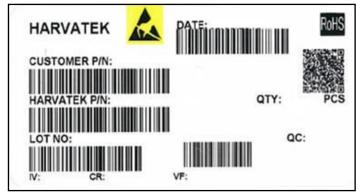
The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

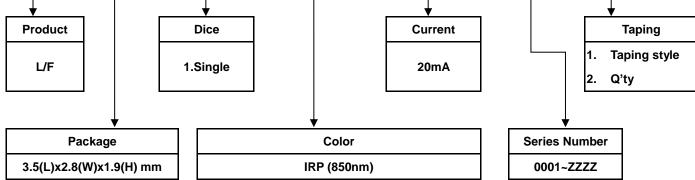
	7				
	Official Product	HT Part No.T16P1IRP-20C-0006X2			
	Tentative Product	******			
ſ	Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 4/15

## **Label Specifications**



■Harvatek P/N:





### Lot No.:

1	2	3	4	5	6	7	8	9	10
E	1	Α	1	Α	2	2	L	1	2
Cod	le 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
		Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number	1	Special cod	e
		2010-A		1:A					
		2011-B	SV 101	2:B					
		2012-C	1:Jan.	3:C					
			2:Feb.						
lateral Te	anian Carda	2018-I/J	1.444	26:Z	01	77		000~ZZZ	
internal i r	acing Code	2019-K	A:Oct.	27:7	01-	-ZZ		000~222	
		122	B:Nov.	28:8					
		2022-N	C:Dec.	29:9					
		2023-P	1000000000	30:3					
		2444		31:4					

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 5/15

#### Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
١ <sub>F</sub>	Forward Current	100	mA	
I <sub>FP</sub>	Peak Forward Current	1	А	1
V <sub>R</sub>	Reverse Voltage	5	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	°C	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature	260	°C	2

#### Notes:

- 1.  $I_{FP}$  Conditions--Pulse Width  ${\leq}\,100\mu s$  and Duty  ${\leq}\,1\%.$
- 2. Soldering time  $\leq$  5 seconds.

### **Electro-Optical Characteristics**

Symbol	Parameters	Test conditions	Min	Тур	Max	Units	Notes
l <sub>e</sub>	Radiant Intensity	I <sub>F</sub> =20mA	1.75	-	7.25	mW/sr	3
λ <sub>P</sub>	Peak Wavelength	I <sub>F</sub> =20mA	-	850	-	nm	4
Δλ	Spectral bandwidth at 50% of $I_{max}$	I <sub>F</sub> =20mA		30	-	nm	
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =20mA	-	1.5	1.65	V	5
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	100	μA	
20	Angle of Half Intensity (X)		-	120	-	dog	
20 <sub>1/2</sub>	Angle of Half Intensity (Y)	I <sub>F</sub> =20mA	-	120	-	deg	

#### Notes:

3. Radiant Intensity (Ie) Bin:

Color	Bin Code Spec. Range		
	Е	1.75-2.75 mW/sr	
IRP	F	2.75-4.5 mW/sr	
	G	4.5-7.25 mW/sr	

4. Radiant Intensity (Ie) Bin:

Color	Bin Code	Spec. Range
IRP	D	830-870 nm

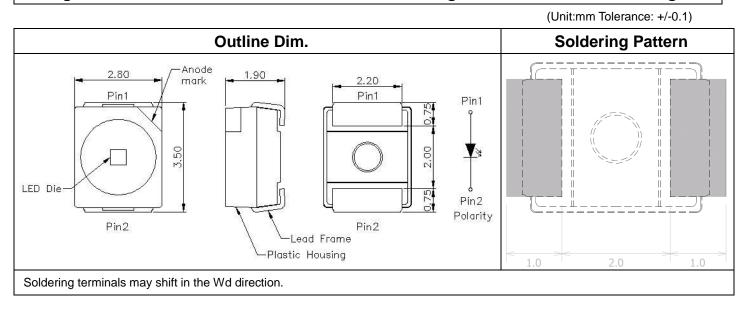
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	**********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 6/15



5. Forward Voltage (V<sub>F</sub>) Bin:

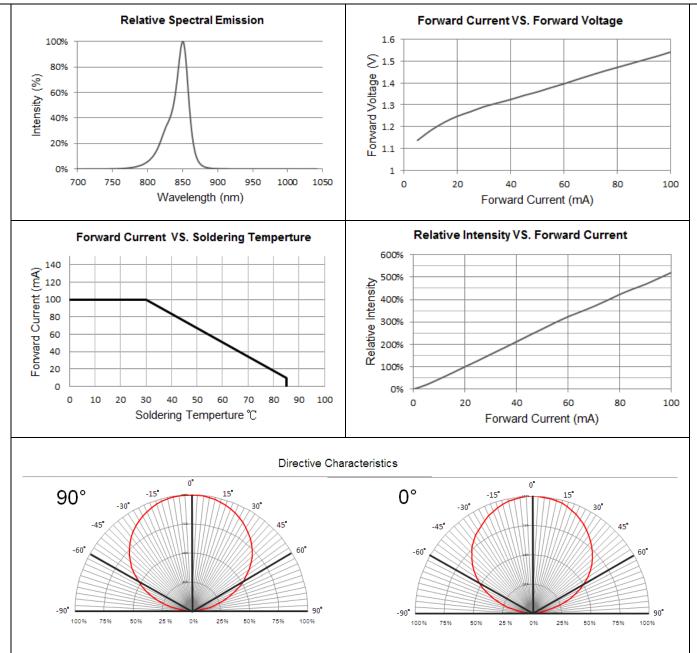
Color	Bin Code	Spec. Range
IRP	D23T	1.35-1.65 V

## Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering



7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	***************************************			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 7/15

### Characteristics of T16P1IRP



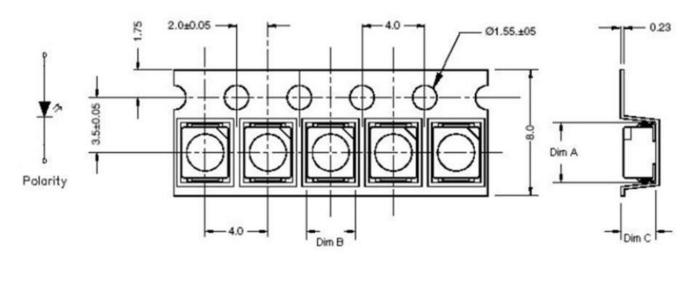
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	***************************************			
	t to changes for improvement without advance awings, company confidential all rights reserved.	02/25/2020	Version 1.1	Page 8/15

#### Precaution for Use

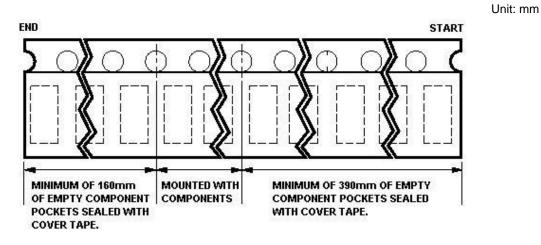
- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 72 hrs after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs.If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs.Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	******	*****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	02/25/2020	Version 1.1	Page 9/15

## Packaging Tape Dimension

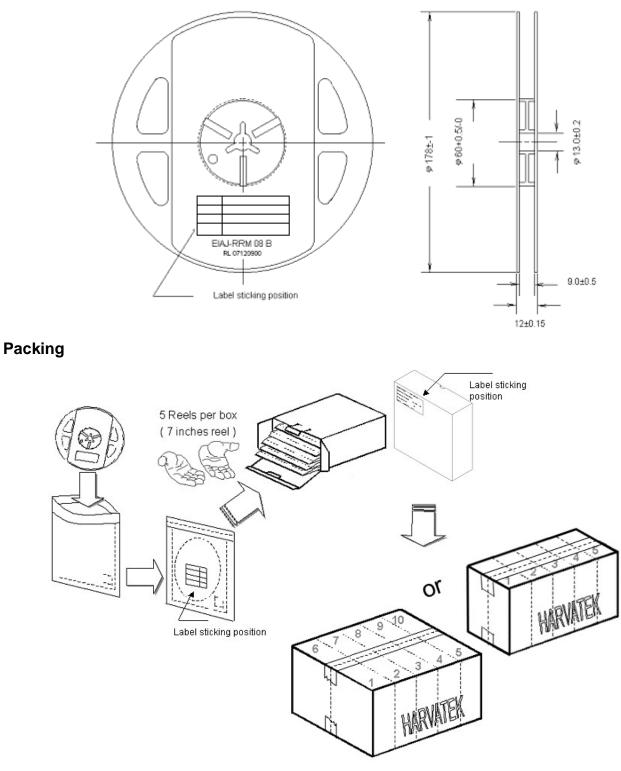


Dim. A	Dim. B	Dim. C	Q'ty/Reel
3.73±0.10	2.95±0.10	2.12±0.10	2K



Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 10/15

## **Reel Dimension**



#### 5 or 10 boxes per carton is available depending on shipment quantity.

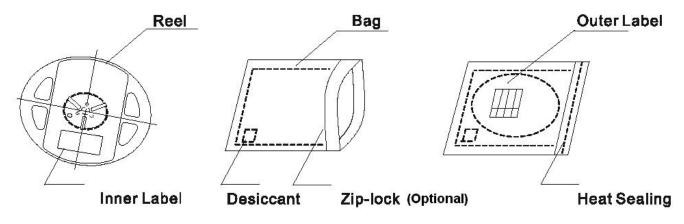
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	02/25/2020	Version 1.1	Page 11/15

### Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



## Baking

Baking before soldering is recommended when the package has been unsealed for 72 hrs. The conditions are as followings:

- 1.  $60\pm3^{\circ}C\times(12\sim24hrs)$  and <5% RH, taped reel type.
- 2. 100±3°C ×(45min~1hr), bulk type.
- 3. 130±3°C ×(15min~30min), bulk type.

## Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	02/25/2020	Version 1.1	Page 12/15

## Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible.

Sharp objects of all types should not be used to pierce the sealing compound.



Figure 1

In general, LEDs should only be handled from the side. By the way ,this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

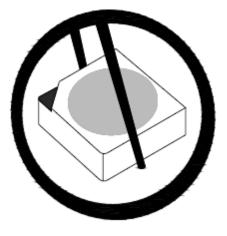


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the from of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.

This is assured by choosing a pick and place nozzle which is large than LEDs reflector area.

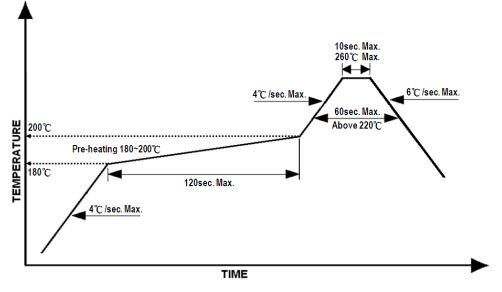
Official Product HT Part No.T16P1IRP-20C-0006X2				
Tentative Product	***************************************			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 13/15

## **Reflow Soldering**

Recommend soldering paste specifications:

- 1. Operating temp.: Above 220 <sup>O</sup>C ,60 sec.
- 2. Peak temp.:260 <sup>O</sup>CMax.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



### Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

## Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 <sup>O</sup>C max, <3min

7				
Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	*****	****		
	t to changes for improvement without advance awings, company confidential all rights reserved.	02/25/2020	Version 1.1	Page 14/15

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

#### **Revise History**

Rev.	Descriptions	Date	Page
1.0	-	10/06/2017	-
1.1	New Lot No.	02/25/2020	5

Official Product	HT Part No.T16P1IRP-20C-0006X2			
Tentative Product	*****	****		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		02/25/2020	Version 1.1	Page 15/15